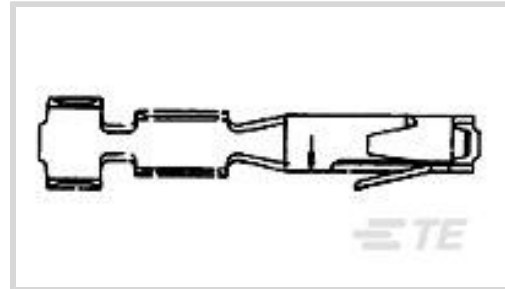




Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Connector Contacts



Contact Type: **Socket**

Connector System: **Cable-to-Cable**

Contact Mating Area Plating Material: **Gold**

Wire Size: **.03 – .09 mm²**

Features

Product Type Features

Applied Pressure	Standard
Connector System	Cable-to-Cable
Sealable	No
Connector & Contact Terminates To	Wire & Cable

Contact Features

Contact Mating Area Plating Material Thickness	1.25 μm[49.2 μin]
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Phosphor Bronze
Contact Type	Socket
Contact Mating Area Plating Material	Gold
Contact Orientation	Straight
Contact Current Rating (Max)	3 A

Termination Features

Termination Method to Wire & Cable	Crimp
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Mechanical Attachment

Wire Insulation Support	With
PCB Mount Retention	Without
Connector Mounting Type	Cable Mount (Free-Hanging)

Dimensions

Accepts Wire Insulation Diameter Range	.5 – 1.02 mm[.02 – .04 in]
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Wire Size	.03 – .09 mm ²
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Usage Conditions

Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
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Operation/Application

Circuit Application	Power & Signal
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Packaging Features

Packaging Quantity	14000
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Packaging Method	Reel
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Not applicable for solder process capability
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Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_167041-2_M.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_167041-2_M.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_167041-2_M.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English